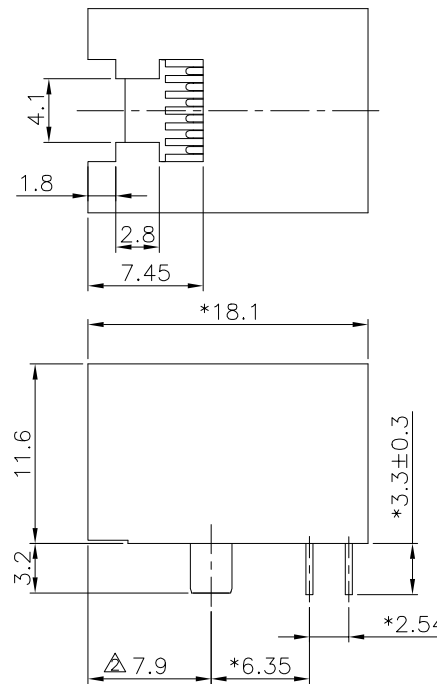
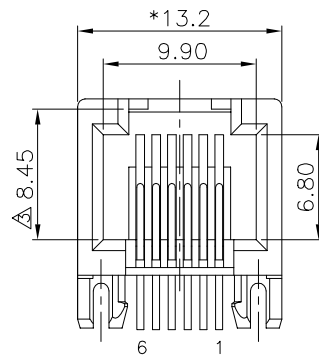


PC Board Layout t=1.60mm
Component Side Shown



REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD
△		DRAWING MODIFY	JACKEY 7/1/99	
△		7.9 was 8.0	JACKEY 7/14/99	H
△		Add P/N	LUSHENG 01/16/01	
△		DRAWING MODIFY	CZH 7/15/02	
△		DRAWING MODIFY	CZH 02/08/03	
△		DRAWING MODIFY	SAMMY 02/02/04	
△		Add P/N	Ying 21/05/04	
△		Add P/N	SHE 7/13/04	G
△		Add P/N	CXG 5/05/05	

NOTES:

ELECTRICAL:

1. VOLTAGE RATING : 150 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 20 MILLIOHMS MAX.
- △ 4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. HOUSING MATERIAL : GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE Ø0.46mm.
3. PLATING : GOLD PLATING OVER NICKEL.
- △ 4. OPERATING LIFE : 750 CYCLES MIN.
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POST-SOLDER: 10 LBS MIN.

ENVIRONMENTAL:

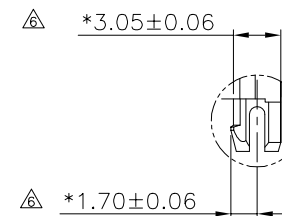
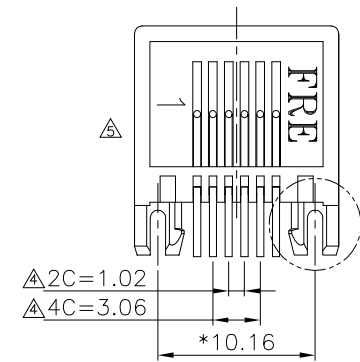
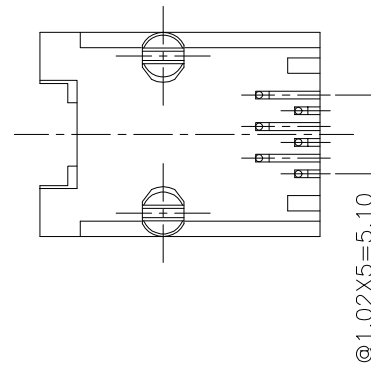
1. STORAGE : -40°C TO +85°C.
 2. OPERATION: -20°C TO 85°C.
- MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.
CUL FILE NO. E163191

PART NUMBER: E536X-300XGX

2- 2C
4- 4C
6- 6C

1- 3u" 2- 6u" 3-15u"
4- 30u" 5-50u" F-Glod flash

MATERIAL OF HS'G :
0- PBT + G.F.BK.
△ 4-FR50 BK
△ 5-FR52 BK



DETACHED LISTS	← MM (INCH) →		DFTO BASS	DATE 8/28/98	FULL RISE ELECTRONIC CO., LTD	
	TOLERANCES EXCEPT AS NOTED		CHKD	DATE		
	MM	±	MFO	DATE	TITLE 11.5mm SIDE PCB JACK 6P	
	.0 ±0.2	±	APPVL XLF	DATE 05/05/05		
.00 ±0.15	±	MATERIAL :		DRAWING NO. GE533022	SIZE A3	REV 9
.000 ±0.075	±	ANGLES ± 0.5		/PART NO. SEE NOTE		
THIRD ANGLE PROJECTION		SCALE : 3 : 1		DO NOT SCALE DRAWING		SHEET 1 OF 1